

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

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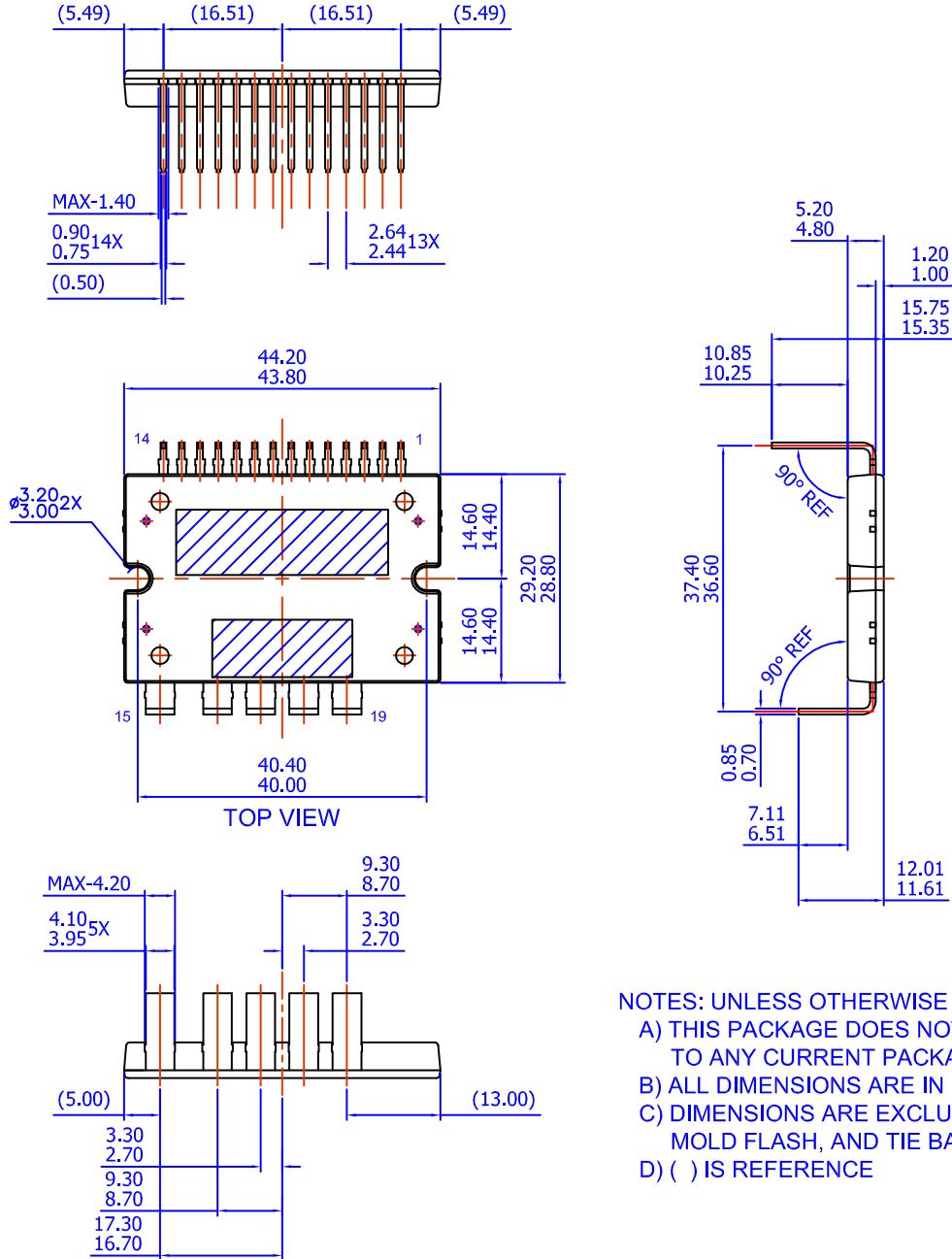


APMCB-A19 / 19LD, APM, PDD STD DBC, DIP TYPE

CASE MODCG

ISSUE O

DATE 31 DEC 2016



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
 - B) ALL DIMENSIONS ARE IN MILLIMETERS
 - C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
 - D) () IS REFERENCE

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